# **MOSFET** – Single, N-Channel, Small Signal, **SOT-23** 30 V, 0.56 A

### **Features**

- Low Gate Voltage Threshold (V<sub>GS(TH)</sub>) to Facilitate Drive Circuit Design
- Low Gate Charge for Fast Switching
- ESD Protected Gate
- SOT-23 Package Provides Excellent Thermal Performance
- Minimum Breakdown Voltage Rating of 30 V
- NVR Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### **Applications**

- Notebooks:
  - Level Shifters
  - Logic Switches
  - Low Side Load Switches
- Portable Applications

## MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	30	V
Gate-to-Source Voltage			$V_{GS}$	±20	V
Continuous Drain	Steady	T <sub>A</sub> = 25°C	I <sub>D</sub>	0.5	Α
Current (Note 1)	State	T <sub>A</sub> = 85°C		0.37	
Power Dissipation (Note 1)	Steady State		P <sub>D</sub>	0.69	W
Continuous Drain	t < 10 s	t < 10 s T <sub>A</sub> = 25°C		0.56	Α
Current (Note 1)		T <sub>A</sub> = 85°C		0.40	
Power Dissipation (Note 1)	t < 5 s		P <sub>D</sub>	0.83	W
Pulsed Drain Current	t <sub>p</sub> =	: 10 μs	I <sub>DM</sub>	1.7	Α
Operating Junction and Storage Temperature			T <sub>J</sub> , Tstg	–55 to 150	°C
Source Current (Body Diode)			Is	1.0	Α
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

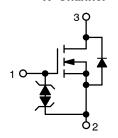


# ON Semiconductor®

#### www.onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> MAX
30 V	1.0 Ω @ 4.0 V	0.56 A
	1.5 Ω @ 2.5 V	0.007.

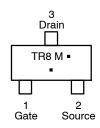
#### N-Channel



## **MARKING DIAGRAM/ PIN ASSIGNMENT**



SOT-23 **CASE 318** STYLE 21



TR8 = Specific Device Code

Μ = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and overbar may vary depending upon manufacturing location.

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTR4003NT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NTR4003NT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel
NVR4003NT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	180	°C/W
Junction-to-Ambient - t < 10 s (Note 1)	$R_{\theta JA}$	150	
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	300	

Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).
 Surface-mounted on FR4 board using the minimum recommended pad size.

# **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Cond	lition	Min	Тур	Max	Units
OFF CHARACTERISTICS			•		•		•
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = 100 \mu\text{A}$		30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>				40		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 30 V				1.0	μА
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS}$	s = ±10 V			±1.0	μΑ
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{D}$	= 250 μΑ	8.0		1.4	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				3.4		mV/°C
Drain-to-Source On Resistance	-	$V_{GS} = 4.0 \text{ V}, I_D = 10 \text{ mA}$			1.0	1.5	Ω
	R <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V}, I_{D} = 10 \text{ mA}$			1.5	2.0	
Forward Transconductance	9 <sub>FS</sub>	$V_{DS} = 3.0 \text{ V}, I_{D} = 10 \text{ mA}$			0.33		S
CHARGES AND CAPACITANCES							
Input Capacitance	C <sub>iss</sub>				21	42	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V, f} = V_{DS} = 5$	1.0 MHz, 5.0 V		19.7	40	
Reverse Transfer Capacitance	C <sub>rss</sub>	53			8.1	16	
Total Gate Charge	Q <sub>G(TOT)</sub>				1.15		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>	$V_{GS} = 5.0 \text{ V}, V_{\Gamma}$	os = 24 V,		0.15		
Gate-to-Source Gate Charge	Q <sub>GS</sub>	$V_{GS} = 5.0 \text{ V}, V_{E}$ $I_{D} = 0.7$	1 A		0.32		
Gate-to-Drain Charge	Q <sub>GD</sub>				0.23		
SWITCHING CHARACTERISTICS (Note	4)						
Turn-On Delay Time	t <sub>d(on)</sub>				16.7		
Rise Time	t <sub>r</sub>	$V_{GS} = 4.5 \text{ V}, V_{DD} = 5.0 \text{ V},$ $I_{D} = 0.1 \text{ A}, R_{G} = 50 \Omega$			47.9		ns
Turn-Off Delay Time	t <sub>d(off)</sub>				65.1		
Fall Time	t <sub>f</sub>				64.2		
SOURCE-DRAIN DIODE CHARACTERI	STICS		•				
Forward Diode Voltage	$V_{SD}$	$V_{GS} = 0 V$	T <sub>J</sub> = 25°C		0.65	0.7	V
		$I_S = 10 \text{ mA}$	T <sub>J</sub> = 125°C		0.45		
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = 0 \text{ V, } dI_{S}/dt = 8A/\mu s,$ $I_{S} = 10 \text{ mA}$			14		ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width  $\leq 300~\mu s$ , duty cycle  $\leq 2\%$ .

4. Switching characteristics are independent of operating junction temperatures.

# TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)

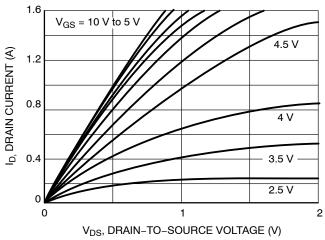


Figure 1. On-Region Characteristics

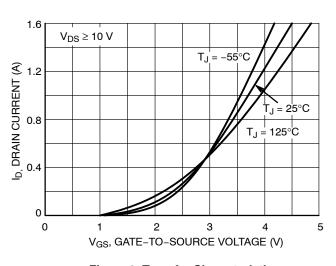


Figure 2. Transfer Characteristics

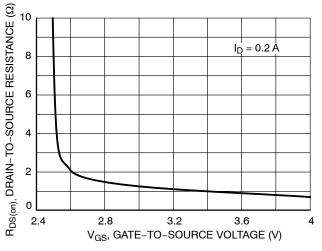


Figure 3. On-Resistance vs. Gate-to-Source Voltage

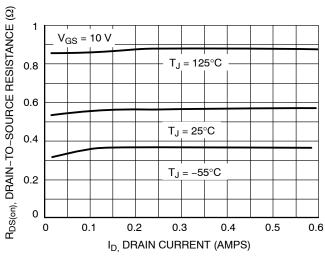


Figure 4. On–Resistance vs. Drain Current and Temperature

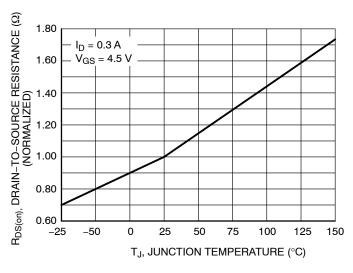


Figure 5. On–Resistance Variation with Temperature

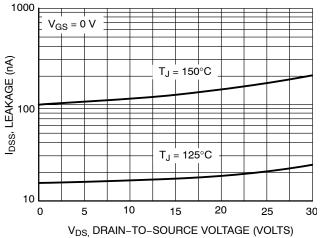


Figure 6. Drain-to-Source Leakage Current vs. Voltage

# TYPICAL PERFORMANCE CURVES ( $T_J = 25^{\circ}C$ unless otherwise noted)

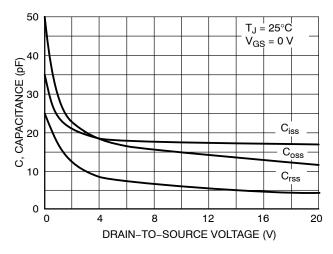


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source & Drain-to-Source Voltage vs. Total Charge

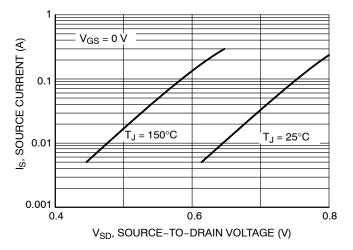
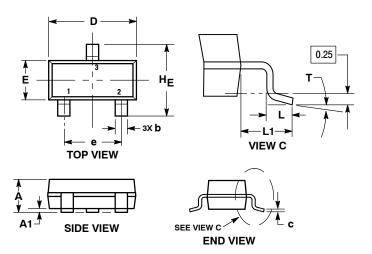


Figure 9. Diode Forward Voltage vs. Current

### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR** 



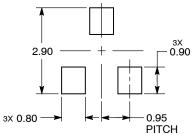
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
  MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
T	0°		10°	0°		10°

STYLE 21:

- PIN 1. GATE 2. SOUR
  - SOURCE
  - DRAIN

## **RECOMMENDED SOLDERING FOOTPRINT\***



**DIMENSIONS: MILLIMETERS** 

ON Semiconductor and (III) are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="https://www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor, "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

### **PUBLICATION ORDERING INFORMATION**

## LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Phone: 81-3-5817-1050

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.